Phototransistors

Panasonic

PNZ155 (PN155)

Silicon planar type

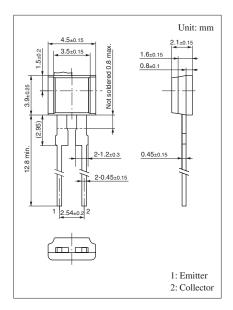
For optical control systems

Features

- High sensitivity
- Wide spectral sensitivity characteristics, suited for detecting GaAs LEDs
- Low dark current
- Flat type plastic package

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Symbol	Rating	Unit	
V _{CEO}	20	V	
V_{ECO}	5	V	
I _C	10	mA	
P _C	100	mW	
T _{opr}	-25 to +85	°C	
T _{stg}	-30 to +100	°C	
	V _{CEO} V _{ECO} I _C P _C T _{opr}	$\begin{array}{c c} V_{CEO} & 20 \\ V_{ECO} & 5 \\ I_C & 10 \\ P_C & 100 \\ T_{opr} & -25 \text{ to } +85 \end{array}$	



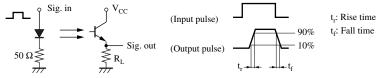
Electrical-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

1	a					
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Photocurrent *1	I _{CE(L)}	$V_{CE} = 10 \text{ V}, L = 100 \text{ lx}$	0.05	0.20		μΑ
Dark current	I _{CEO}	$V_{CE} = 10 \text{ V}$		0.01	1.00	μΑ
Peak emission wavelength	λ_p	$V_{CE} = 10 V$		800		nm
Half-power angle	θ	The angle from which photocurrent becomes 50%		70		0
Rise time *2	t _r	$V_{CC} = 10 \text{ V}, \text{ I}_{CE(L)} = 1 \text{ mA}, \text{ R}_{L} = 100 \Omega$		4		μs
Fall time *2	t _f			4		μs
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_{CE(L)} = 1 \text{ mA}, L = 1000 \text{ lx}$		0.2	0.5	V

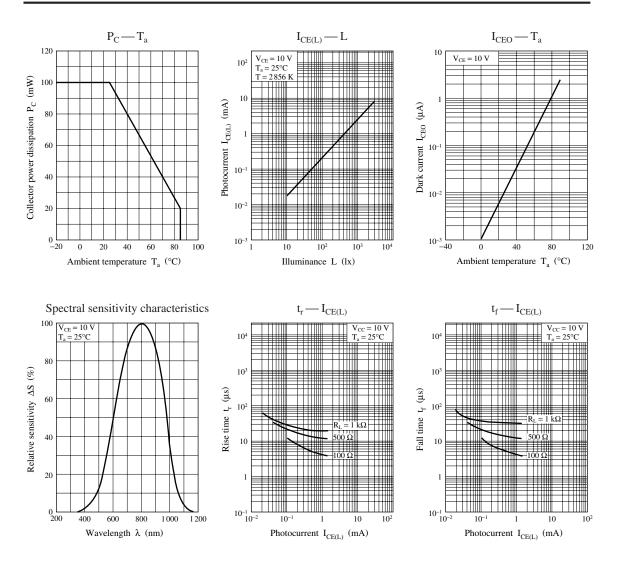
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. Spectral sensitivity characteristics: Sensitivity for wave length over 400 nm maximum sensitivity ratio is 100%.

- 3. This device is designed be disregarded radiation.
- 4. *1: Source: Tungsten (color temperature 2856 K)
 - *2: Switching time measurement circuit



Note) The part number in the parenthesis shows conventional part number.



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